

IN THE CLAIMS:

Please CANCEL claims 1-4, 8-11 and 15 without prejudice to or disclaimer of the recited subject matter.

Please AMEND claims 5-7 and 12-14, as follows. For the Examiner's convenience, all claims currently pending have been reproduced below.

1-4. (Canceled)

5. (Currently Amended) The apparatus according to claim 2 A substrate alignment apparatus which aligns and fixes a substrate on a substrate stage, said apparatus comprising:

a chucking pad fixed on the substrate stage to chuck and fix a substrate;

a moving unit which moves the substrate with respect to the substrate stage such

that a mark on the substrate stage and a mark on the substrate coincide with each other, wherein

said moving unit has (i) a first unit which aligns the substrate with reference to an outer shape of

the substrate, and (ii) a second unit which detects the mark drawn on the substrate and moves the

substrate by a shift from the mark on the substrate stage; and

a determination unit which evaluates and controls a relative position between said

chucking pad and the substrate after movement by said moving unit and determines whether said

chucking pad can chuck the substrate, wherein said determination unit evaluates and controls the

relative position on the basis of an amount by which the second unit moves the substrate,

wherein if said determination unit determines that said chucking pad cannot

normally chuck the substrate, the amount by which the second unit moves the substrate is limited

to a value within a range which enables said chucking pad to normally chuck the substrate.

6. (Currently Amended) The apparatus according to claim 3 A substrate alignment apparatus which aligns and fixes a substrate on a substrate stage, said apparatus comprising:

a chucking pad fixed on the substrate stage to chuck and fix a substrate;

a moving unit which moves the substrate with respect to the substrate stage such that a mark on the substrate stage and a mark on the substrate coincide with each other, wherein said moving unit has (i) a first unit which aligns the substrate with reference to an outer shape of the substrate, and (ii) a second unit which detects the mark drawn on the substrate and moves the substrate by a shift from the mark on the substrate stage; and

a determination unit which evaluates and controls a relative position between said chucking pad and the substrate after movement by said moving unit and determines whether said chucking pad can chuck the substrate, wherein said determination unit evaluates and controls the relative position on the basis of an amount by which the second unit moves the substrate, wherein the first unit is arranged on a stage separate from the substrate stage, the second unit is arranged on the substrate stage, and if said determination unit determines that said chucking pad cannot normally chuck the substrate, alignment of the substrate is stopped.

7. (Currently Amended) The apparatus according to claim 4 A substrate alignment apparatus which aligns and fixes a substrate on a substrate stage, said apparatus comprising:

a chucking pad fixed on the substrate stage to chuck and fix a substrate;

a moving unit which moves the substrate with respect to the substrate stage such that a mark on the substrate stage and a mark on the substrate coincide with each other, wherein said moving unit has (i) a first unit which aligns the substrate with reference to an outer shape of

the substrate, and (ii) a second unit which detects the mark drawn on the substrate and moves the substrate by a shift from the mark on the substrate stage; and

a determination unit which evaluates and controls a relative position between said chucking pad and the substrate after movement by said moving unit and determines whether said chucking pad can chuck the substrate, wherein said determination unit evaluates and controls the relative position on the basis of an amount by which the second unit moves the substrate, wherein the first and second units are arranged on a stage separate from the substrate stage, and if said determination unit determines that said chucking pad cannot normally chuck the substrate, transportation of the substrate to the substrate stage is stopped.

8-11. (Canceled)

12. (Currently Amended) The method according to claim 9 A substrate alignment method of aligning and fixing a substrate on a substrate stage by using a chucking pad fixed on the substrate stage to chuck and fix a substrate, said method comprising:

a moving step of moving the substrate with respect to the substrate stage such that a mark on the substrate stage and a mark on the substrate coincide with each other; and a determination step of evaluating and controlling a relative position between the chucking pad and the substrate after movement in the moving step, and determining whether the chucking pad can chuck the substrate,

wherein if it is determined in the determination step that the chucking pad cannot normally chuck the substrate, the moving amount in the second step is limited to a value within a range which enables the chucking pad to normally chuck the substrate.

13. (Currently Amended) ~~The method according to claim 10~~ A substrate alignment method of aligning and fixing a substrate on a substrate stage by using a chucking pad fixed on the substrate stage to chuck and fix a substrate, said method comprising:

a moving step of moving the substrate with respect to the substrate stage such that a mark on the substrate stage and a mark on the substrate coincide with each other; and a determination step of evaluating and controlling a relative position between the chucking pad and the substrate after movement in the moving step, and determining whether the chucking pad can chuck the substrate,

wherein the first step is performed on a stage separate from the substrate stage, and the second step is performed on the substrate stage, and if it is determined in the determination step that the chucking pad cannot normally chuck the substrate, alignment of the substrate is stopped.

14. (Currently Amended) ~~The method according to claim 11~~ A substrate alignment method of aligning and fixing a substrate on a substrate stage by using a chucking pad fixed on the substrate stage to chuck and fix a substrate, said method comprising:

a moving step of moving the substrate with respect to the substrate stage such that a mark on the substrate stage and a mark on the substrate coincide with each other; and a determination step of evaluating and controlling a relative position between the chucking pad and the substrate after movement in the moving step, and determining whether the chucking pad can chuck the substrate,

wherein the first and second steps are performed on a stage separate from the substrate stage and, if it is determined in the determination step that the chucking pad cannot normally chuck the substrate, transportation of the substrate to the substrate stage is stopped.

15. (Canceled)